

# 2.9 nV/sqrt(Hz) Low Noise, Precision, RRIO Amplifier

Check for Samples: LMP7731

### **FEATURES**

(Typical Values,  $T_A = 25$ °C,  $V_S = 5V$ )

- Input Voltage Noise
  - f = 3 Hz 3.3 nV/ $\sqrt{\text{Hz}}$
  - f = 1 kHz 2.9 nV/ $\sqrt{\text{Hz}}$
- CMRR 130 dB
- Open Loop Gain 130 dB
- GBW 22 MHz
- Slew Rate 2.4 V/µs
- THD @ f = 10 kHz,  $A_V = +1$ ,  $R_L = 2 k\Omega 0.001\%$
- Supply Current per Channel 2.2 mA
- Supply Voltage Range 1.8V to 5.5V
- Operating Temperature Range -40°C to 125°C
- Input Bias Current ±1.5 nA
- RRIO

#### **APPLICATIONS**

- Gas Analysis Instruments
- Photometric Instrumentation
- Medical Instrumentation

#### DESCRIPTION

The LMP7731 is a single, low noise, rail-to-rail input and output, low voltage amplifier. The LMP7731 is part of the LMP™ precision amplifier family and is ideal for precision and low noise applications with low voltage requirements.

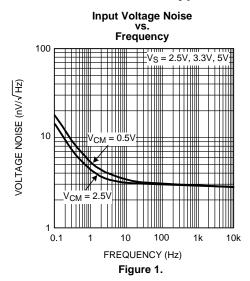
This operational amplifier offers low voltage noise of 2.9 nV/ $\sqrt{\text{Hz}}$  with a 1/f corner of only 3 Hz. The LMP7731 has bipolar input stages with a bias current of only 1.5 nA. This low input bias current, complemented by the very low level of voltage noise, makes the LMP7731 an excellent choice for photometry applications.

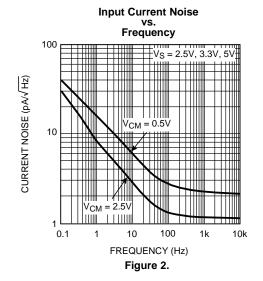
The LMP7731 provides a wide GBW of 22 MHz while consuming only 2 mA of current. This high gain bandwidth along with the high open loop gain of 130 dB enables accurate signal conditioning in applications with high closed loop gain requirements.

The LMP7731 has a supply voltage range of 1.8V to 5.5V, making it an ideal choice for battery operated portable applications.

The LMP7731 is offered in the space saving 5-Pin SOT-23 and 8-Pin SOIC packages.

### **Typical Performance Characteristics**





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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# Absolute Maximum Ratings (1)(2)

	<u> </u>		
ESD Tolerance (3)	Human Body Model	Inputs pins only	2000V
		All other pins	2000V
	Machine Model		200V
	Charge Device Model		1000V
V <sub>IN</sub> Differential			±2V
Supply Voltage $(V_S = V^+ - V^-)$			6.0V
Storage Temperature Range			−65°C to 150°C
Junction Temperature (4)			+150°C max
Soldering Information	Infrared or Convection (2	0 sec)	235°C
	Wave Soldering Lead Te	mp. (10 sec)	260°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics Tables.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (3) Human Body Model, applicable std. MIL-STD-883, Method 3015.7. Machine Model, applicable std. JESD22-A115-A (ESD MM std. of JEDEC)Field-Induced Charge-Device Model, applicable std. JESD22-C101-C (ESD FICDM std. of JEDEC).
- (4) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} T_A)/\theta_{JA}$ . All numbers apply for packages soldered directly onto a PC Board.

### Operating Ratings (1)

Temperature Range	-40°C to 125°C	
Supply Voltage $(V_S = V^+ - V^-)$	1.8V to 5.5V	
Package Thermal Resistance (θ <sub>JA</sub> )	5-Pin SOT-23	265°C/W
	8-Pin SOIC	190°C/W

<sup>(1)</sup> Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics Tables.

### 2.5V Electrical Characteristics (1)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 2.5V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10 \text{ k}\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

	Parameter	Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units
V	Input Offset Voltage	V <sub>CM</sub> = 2.0V		±9	±500 <b>±600</b>	\/
vos	Vos (4)	V <sub>CM</sub> = 0.5V		±9	±500 <b>±600</b>	μV
TCV	Input Offset Voltage Temperature	$V_{CM} = 2.0V$		±0.5	±5.5	μV/°C
TCV <sub>OS</sub>	Drift	$V_{CM} = 0.5V$		±0.2	±5.5	μν/ С
	Input Digg Current	V <sub>CM</sub> = 2.0V		±1	±30 <b>±45</b>	nA
I <sub>B</sub>	Input Bias Current	V <sub>CM</sub> = 0.5V		±12	±50 <b>±75</b>	IIA

- (1) Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T<sub>J</sub> = T<sub>A</sub>. No specification of parametric performance is indicated in the electrical tables under conditions of internal self-heating where T<sub>J</sub> > T<sub>A</sub>. Absolute maximum Ratings indicate junction temperature limits beyond which the device maybe permanently degraded, either mechanically or electrically.
- (2) All limits are specified by testing, statistical analysis or design.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not ensured on shipped production material.
- 4) Ambient production test is performed at 25°C with a variance of ±3°C.



# 2.5V Electrical Characteristics (1) (continued)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 2.5V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10 \text{ k}\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

	Parameter	Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units	
	In root Officet Coursest	V <sub>CM</sub> = 2.0V		±1	±50 <b>±75</b>	^	
los	Input Offset Current	V <sub>CM</sub> = 0.5V		±11	±60 <b>±80</b>	nA	
TCI <sub>OS</sub>	Input Offset Current Drift	V <sub>CM</sub> = 0.5V and V <sub>CM</sub> = 2.0V		0.0474		nA/°C	
	0	$0.15V \le V_{CM} \le 0.7V$ $0.23V \le V_{CM} \le 0.7V$	101 <b>89</b>	120			
CMRR	Common Mode Rejection Ratio	$1.5V \le V_{CM} \le 2.35V$ $1.5V \le V_{CM} \le 2.27V$	105 <b>99</b>	129		dB	
PSRR	Power Supply Rejection Ratio	2.5V ≤ V <sup>+</sup> ≤ 5V	111 <b>105</b>	129		dB	
	, , , , , , , , , , , , , , , , , , ,	1.8V ≤ V <sup>+</sup> ≤ 5.5V		117			
CMVR	Common Mode Voltage Range	Large Signal CMRR ≥ 80 dB	0		2.5	V	
^	On an Lagra Valtage Coin	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$ $V_{OUT} = 0.5 \text{V to } 2.0 \text{V}$	112 <b>104</b>	130		40	
A <sub>VOL</sub>	Open Loop Voltage Gain	$R_L = 2 k\Omega \text{ to V}^+/2$ $V_{OUT} = 0.5V \text{ to } 2.0V$	109 <b>90</b>	119		- dB	
		$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		4	50 <b>75</b>		
V <sub>OUT</sub>	Output Voltage Swing High	$R_L = 2 k\Omega$ to V <sup>+</sup> /2		13	50 <b>75</b>	mV from	
		$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$	/2 6		50 <b>75</b>	either rail	
	Output Voltage Swing Low	$R_L = 2 \text{ k}\Omega \text{ to V}^+/2$		9	50 <b>75</b>		
	0.1.10	Sourcing, V <sub>OUT</sub> = V <sup>+</sup> /2 V <sub>IN</sub> (diff) = 100 mV	22 <b>12</b>	31			
l <sub>OUT</sub>	Output Current	Sinking, $V_{OUT} = V^+/2$ $V_{IN}$ (diff) = -100 mV	15 <b>10</b>	44		mA	
	Supply Current	V <sub>CM</sub> = 2.0V		2.0	2.7 <b>3.4</b>	^	
I <sub>S</sub>	(Per Channel)	V <sub>CM</sub> = 0.5V		2.3 3.1 <b>3.9</b>		mA	
SR	Slew Rate	$A_V = +1$ , $C_L = 10$ pF, $R_L = 10$ k $\Omega$ to $V^+/2$ , $V_O = 2$ $V_{PP}$		2.4		V/µs	
GBW	Gain Bandwidth	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		21		MHz	
G <sub>M</sub>	Gain Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		14		dB	
ФМ	Phase Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		60		deg	
	Input Peniatanas	Differential Mode		38		kΩ	
R <sub>IN</sub>	Input Resistance	Common Mode		151		ΜΩ	
THD+N	Total Harmonic Distortion + Noise	$A_V = 1$ , $f = 1$ kHz, Amplitude = 1V		0.002		%	
e	Input Referred Voltage Noise Density	$f = 1 \text{ kHz}, V_{CM} = 2.0V$ $f = 1 \text{ kHz}, V_{CM} = 0.5V$		3		nV/√Hz	
e <sub>n</sub>	Input Voltage Noise	0.1 Hz to 10 Hz		75		nV <sub>PP</sub>	
i.	Input Referred Current Noise	f = 1 kHz, V <sub>CM</sub> = 2.0V		1.1		pA/√Hz	
Density		$f = 1 \text{ kHz}, V_{CM} = 0.5V$		2.3		P/ // 11 12	



# 3.3V Electrical Characteristics (1)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 3.3V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10 \text{ k}\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

	Parameter	Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units	
.,	Input Offset Voltage	V <sub>CM</sub> = 2.5V		±6	±500 <b>±600</b>		
V <sub>OS</sub>	(4)	V <sub>CM</sub> = 0.5V		±6	±500 <b>±600</b>	μV	
TOV	Input Offset Voltage Temperature	V <sub>CM</sub> = 2.5V		±0.5	±5.5	\//00	
TCV <sub>OS</sub>	Drift	$V_{CM} = 0.5V$		±0.2	±5.5	μV/°C	
	Input Pige Current	V <sub>CM</sub> = 2.5V		±1.5	±30 <b>±45</b>	n 1	
I <sub>B</sub>	Input Bias Current	V <sub>CM</sub> = 0.5V		±13	±50 <b>±77</b>	- nA	
	Input Offact Current	V <sub>CM</sub> = 2.5V		±1	±50 <b>±70</b>	m A	
los	Input Offset Current	V <sub>CM</sub> = 0.5V		±11	±60 <b>±80</b>	nA	
TCI <sub>OS</sub>	Input Offset Current Drift	$V_{CM} = 0.5V$ and $V_{CM} = 2.5V$	_	0.048		nA/°C	
CMDD	Common Mada Daiastica Datia	$0.15V \le V_{CM} \le 0.7V$ $0.23V \le V_{CM} \le 0.7V$	101 <b>89</b>	120		40	
CMRR	Common Mode Rejection Ratio	$1.5V \le V_{CM} \le 3.15V$ $1.5V \le V_{CM} \le 3.07V$	105 <b>99</b>	130		dB	
PSRR	Power Supply Rejection Ratio	2.5V ≤ V <sup>+</sup> ≤ 5.0V	111 <b>105</b>	129		dB	
	,,,,,	1.8V ≤ V <sup>+</sup> ≤ 5.5V		117			
CMVR	Common Mode Voltage Range	Large Signal CMRR ≥ 80 dB	0		3.3	V	
۸	Open Lean Valtage Coin	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$ $V_{OUT} = 0.5 \text{V to } 2.8 \text{V}$	112 <b>104</b>	130		٩D	
A <sub>VOL</sub>	Open Loop Voltage Gain	$R_L = 2 k\Omega \text{ to V}^+/2$ $V_{OUT} = 0.5V \text{ to } 2.8V$	110 <b>92</b>	119		- dB	
	Output Valtage Cuing High	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		5	50 <b>75</b>		
	Output Voltage Swing High	$R_L = 2 \text{ k}\Omega \text{ to V}^+/2$		14	50 <b>75</b>	mV from	
V <sub>OUT</sub>	Output Valtage Cuine Laur	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		9	50 <b>75</b>	either rail	
	Output Voltage Swing Low	$R_L = 2 k\Omega$ to $V^+/2$		13	50 <b>75</b>		
	0.4.4.0	Sourcing, V <sub>OUT</sub> = V+/2 V <sub>IN</sub> (diff) = 100 mV	28 <b>22</b>	45		4	
l <sub>OUT</sub>	Output Current	Sinking, V <sub>OUT</sub> = V+/2 25 V <sub>IN</sub> (diff) = -100 mV <b>20</b>		48		- mA	
	Supply Current	V <sub>CM</sub> = 2.5V		2.1	2.8 <b>3.5</b>	- A	
I <sub>S</sub>	(Per Channel)	V <sub>CM</sub> = 0.5V		2.4	3.2 <b>4.0</b>	mA	
SR	Slew Rate	$A_V = +1$ , $C_L = 10$ pF, $R_L = 10$ k $\Omega$ to $V^+/2$ , $V_{OUT} = 2$ $V_{PP}$		2.4		V/µs	

<sup>(1)</sup> Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T<sub>J</sub> = T<sub>A</sub>. No specification of parametric performance is indicated in the electrical tables under conditions of internal self-heating where T<sub>J</sub> > T<sub>A</sub>. Absolute maximum Ratings indicate junction temperature limits beyond which the device maybe permanently degraded, either mechanically or electrically.

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<sup>(2)</sup> All limits are specified by testing, statistical analysis or design.

Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not ensured on shipped production material.

<sup>(4)</sup> Ambient production test is performed at 25°C with a variance of ±3°C.



# 3.3V Electrical Characteristics (1) (continued)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 3.3V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10 \text{ k}\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

	Parameter	Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units
GBW	Gain Bandwidth	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		22		MHz
G <sub>M</sub>	Gain Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		14		dB
ФМ	Phase Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		62		deg
R <sub>IN</sub>	Innut Decistores	Differential Mode		38		kΩ
	Input Resistance	Common Mode		151		ΜΩ
THD+N	Total Harmonic Distortion + Noise	$A_V = 1$ , $f = 1$ kHz, Amplitude = 1V,		0.002		%
	Input Referred Voltage Noise	f = 1 kHz, V <sub>CM</sub> = 2.5V		2.9		nV/√Hz
e <sub>n</sub>	Density	f = 1 kHz, V <sub>CM</sub> = 0.5V		2.9		nv/γHz
	Input Voltage Noise	0.1 Hz to 10 Hz		65		nV <sub>PP</sub>
	Input Referred Current Noise	f = 1 kHz, V <sub>CM</sub> = 2.5V		1.1		pA/√Hz
'n	Density	f = 1 kHz, V <sub>CM</sub> = 0.5V		2.1		pa/\Hz

## 5V Electrical Characteristics (1)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10 k\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

	Parameter	Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units
.,	Input Offset Voltage	V <sub>CM</sub> = 4.5V		±6	±500 <b>±600</b>	\
V <sub>OS</sub>	(4)	V <sub>CM</sub> = 0.5V		±6	±500 ± <b>600</b>	μV
TCV	Input Offset Voltage Temperature	V <sub>CM</sub> = 4.5V		±0.5	±5.5	\//00
TCV <sub>OS</sub>	Drift	$V_{CM} = 0.5V$		±0.2	±5.5	μV/°C
	Input Dice Current	V <sub>CM</sub> = 4.5V		±1.5	±30 <b>±50</b>	m A
I <sub>B</sub>	Input Bias Current	V <sub>CM</sub> = 0.5V		±14	±50 <b>±85</b>	nA
	In rest Officet Comment	V <sub>CM</sub> = 4.5V		±1	±50 <b>±70</b>	- 0
los	Input Offset Current	V <sub>CM</sub> = 0.5V		±11	±65 ± <b>80</b>	nA
TCI <sub>OS</sub>	Input Offset Current Drift	$V_{CM} = 0.5V$ and $V_{CM} = 4.5V$		0.0482		nA/°C
CMRR	Common Mode Rejection Retio	$0.15V \le V_{CM} \le 0.7V$ $0.23V \le V_{CM} \le 0.7V$	101 <b>89</b>	120		dB
CIVIRR	Common Mode Rejection Ratio	$1.5V \le V_{CM} \le 4.85V$ $1.5V \le V_{CM} \le 4.77V$	105 <b>99</b>	130		αБ
PSRR	Power Supply Rejection Ratio	2.5V ≤ V <sup>+</sup> ≤ 5V	111 <b>105</b>	129		dB
	,	1.8V ≤ V <sup>+</sup> ≤ 5.5V		117		
CMVR	Common Mode Voltage Range	Large Signal CMRR ≥ 80 dB	0		5	V
	Open Lean Voltage Cain	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$ $V_{OUT} = 0.5 \text{V to } 4.5 \text{V}$	112 <b>104</b>	130		
A <sub>VOL</sub>	Open Loop Voltage Gain	$R_L = 2 k\Omega$ to $V^+/2$ $V_{OUT} = 0.5V$ to 4.5V	110 <b>94</b>	119		dB

<sup>(1)</sup> Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T<sub>J</sub> = T<sub>A</sub>. No specification of parametric performance is indicated in the electrical tables under conditions of internal self-heating where T<sub>J</sub> > T<sub>A</sub>. Absolute maximum Ratings indicate junction temperature limits beyond which the device maybe permanently degraded, either mechanically or electrically.

<sup>(2)</sup> All limits are specified by testing, statistical analysis or design.

<sup>(3)</sup> Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not ensured on shipped production material.

<sup>4)</sup> Ambient production test is performed at 25°C with a variance of ±3°C.



# 5V Electrical Characteristics (1) (continued)

Unless otherwise specified, all limits are ensured for  $T_A = 25^{\circ}C$ ,  $V^+ = 5V$ ,  $V^- = 0V$ ,  $V_{CM} = V^+/2$ ,  $R_L > 10$  k $\Omega$  to  $V^+/2$ . **Boldface** limits apply at the temperature extremes.

Parameter		Test Conditions	Min <sup>(2)</sup>	Typ <sup>(3)</sup>	Max <sup>(2)</sup>	Units
	Output Voltage Swing High	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		8	50 <b>75</b>	
	Output Voltage Swing High	$R_L = 2 k\Omega$ to V <sup>+</sup> /2		24	50 <b>75</b>	mV from
V <sub>OUT</sub>	Output Valtaga Cuian Lau	$R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		9	50 <b>75</b>	either rail
	Output Voltage Swing Low	$R_L = 2 \text{ k}\Omega \text{ to V}^+/2$		23	50 <b>75</b>	
	Output Current	Sourcing, V <sub>OUT</sub> = V+/2 V <sub>IN</sub> (diff) = 100 mV	33 <b>27</b>	47		- mA
l <sub>OUT</sub>	Output Current	Sinking, V <sub>OUT</sub> = V+/2 V <sub>IN</sub> (diff) = -100 mV	30 <b>25</b>	49		mA
	Supply Current	V <sub>CM</sub> = 4.5V		2.2	3.0 <b>3.7</b>	- mA
I <sub>S</sub>	(Per Channel)	V <sub>CM</sub> = 0.5V		2.5 3.4 <b>4.2</b>		IIIA
SR	Slew Rate	$A_V = +1$ , $C_L = 10$ pF, $R_L = 10$ k $\Omega$ to $V^+/2$ , $V_{OUT} = 2$ $V_{PP}$		2.4		V/µs
GBW	Gain Bandwidth	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		22		MHz
G <sub>M</sub>	Gain Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		12		dB
ФМ	Phase Margin	$C_L = 20 \text{ pF}, R_L = 10 \text{ k}\Omega \text{ to V}^+/2$		65		deg
<b>D</b>	Land Barietana	Differential Mode		38		kΩ
R <sub>IN</sub>	Input Resistance	Common Mode		151		МΩ
THD+N	Total Harmonic Distortion + Noise	$A_V = 1$ , $f = 1$ kHz, Amplitude = 1V		0.001		%
	Input Referred Voltage Noise	f = 1 kHz, V <sub>CM</sub> = 4.5V		2.9		nV/√ <del>Hz</del>
e <sub>n</sub>	Density	f = 1 kHz, V <sub>CM</sub> = 0.5V		2.9		nv/γ <b>HZ</b>
	Input Voltage Noise	0.1 Hz to 10 Hz		78		$nV_{PP}$
	Input Referred Current Noise	f = 1 kHz, V <sub>CM</sub> = 4.5V		1.1		pA/√ <del>Hz</del>
In	Density	$f = 1 \text{ kHz}, V_{CM} = 0.5 \text{V}$		2.2		pA/VHZ

# **Connection Diagrams**

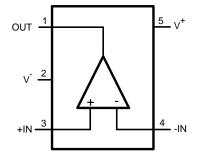


Figure 3. 5-Pin SOT-23 Top View

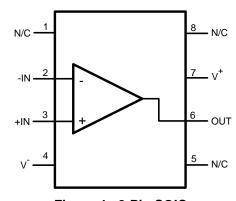


Figure 4. 8-Pin SOIC Top View



## **Typical Performance Characteristics**

Unless otherwise noted:  $T_A = 25$ °C,  $R_L > 10$  k $\Omega$ ,  $V_{CM} = V_S/2$ .

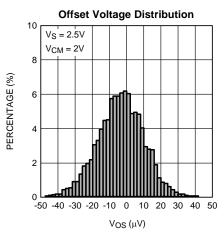


Figure 5.

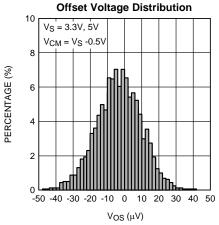
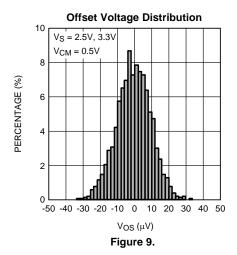


Figure 7.



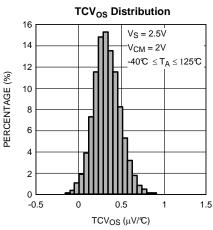
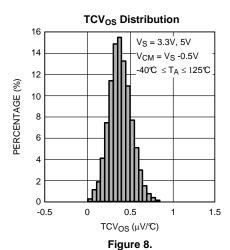
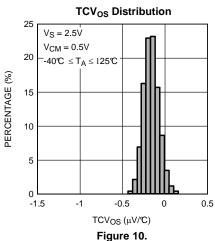


Figure 6.





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Unless otherwise noted:  $T_A$  = 25°C,  $R_L$  > 10 k $\Omega$ ,  $V_{CM}$  =  $V_S/2$ .

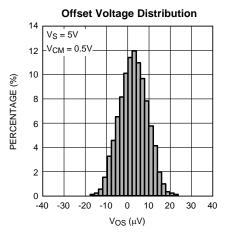


Figure 11.

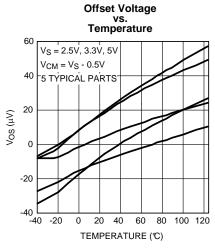


Figure 13.

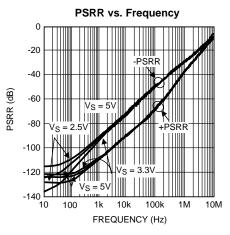


Figure 15.

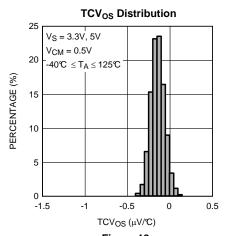


Figure 12.

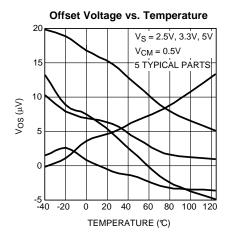


Figure 14.

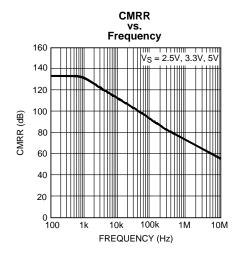


Figure 16.



Unless otherwise noted:  $T_A$  = 25°C,  $R_L$  > 10 k $\Omega$ ,  $V_{CM}$  =  $V_S/2$ .

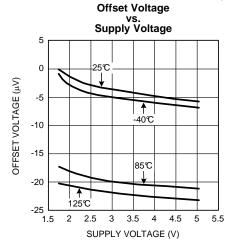
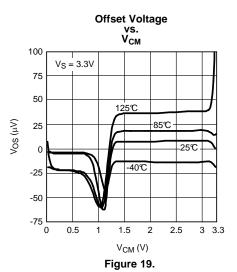
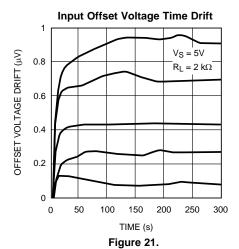


Figure 17.





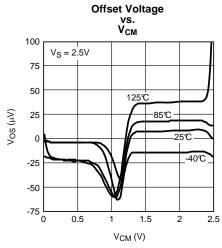


Figure 18.

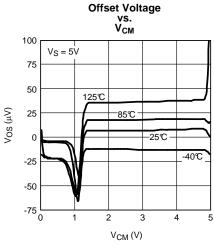


Figure 20.

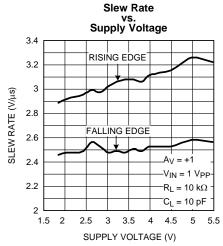


Figure 22.

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Unless otherwise noted:  $T_A = 25^{\circ}C$ ,  $R_L > 10 \text{ k}\Omega$ ,  $V_{CM} = V_S/2$ .

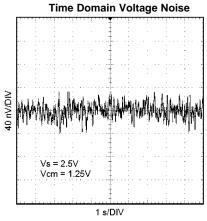


Figure 23.

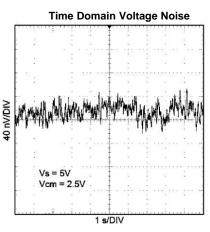


Figure 25.

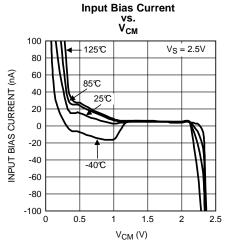


Figure 27.

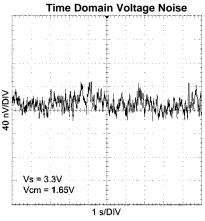
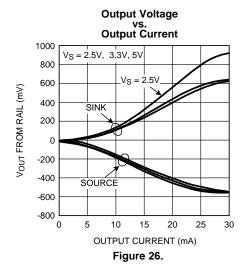


Figure 24.



**Input Bias Current** vs. V<sub>CM</sub> 100 V<sub>S</sub> = 3.3V 125℃ INPUT BIAS CURRENT (nA) 60 40 20 -20 -40 -60 -80 -100 0.5 2 2.5 0 1 1.5 3 3.5 V<sub>CM</sub> (V)

Figure 28.



Unless otherwise noted:  $T_A$  = 25°C,  $R_L$  > 10 k $\Omega$ ,  $V_{CM}$  =  $V_S/2$ .

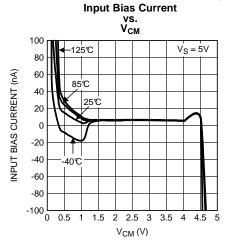
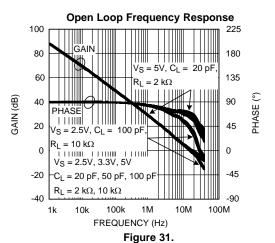


Figure 29.



THD+N

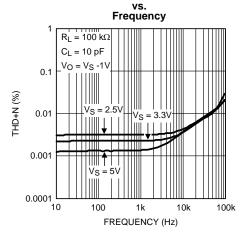


Figure 33.

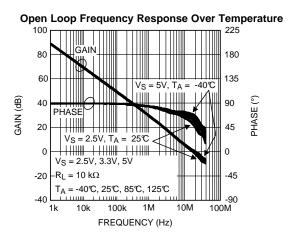


Figure 30.

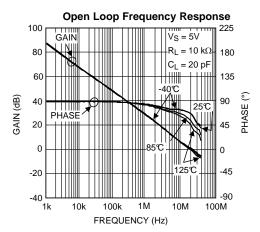


Figure 32.

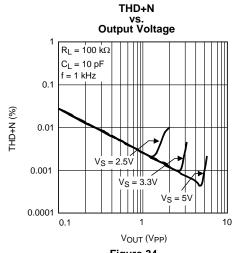


Figure 34.



Unless otherwise noted:  $T_A = 25$ °C,  $R_L > 10 \text{ k}\Omega$ ,  $V_{CM} = V_S/2$ .

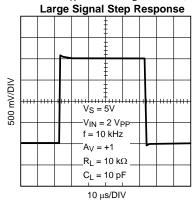


Figure 35.

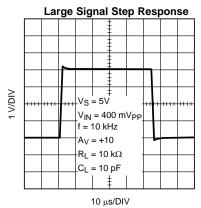
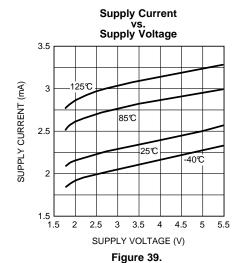


Figure 37.



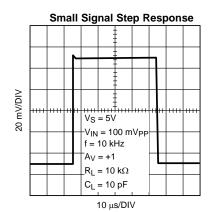


Figure 36.

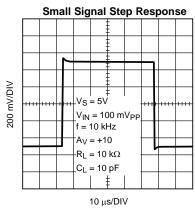
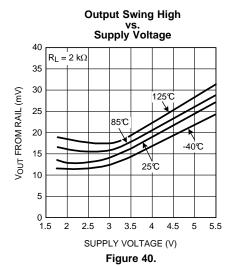
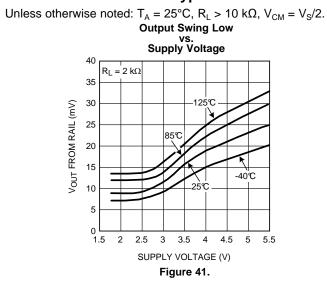
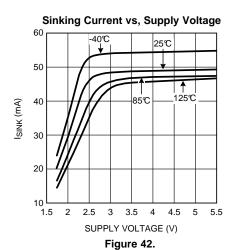


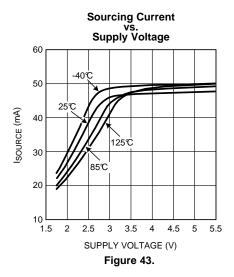
Figure 38.











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#### APPLICATION INFORMATION

#### LMP7731

The LMP7731 is a single, low noise, rail-to-rail input and output, and low voltage amplifier.

The low input voltage noise of only 2.9 nV/ $\sqrt{\text{Hz}}$  with a 1/f corner at 3 Hz makes the LMP7731 ideal for sensor applications where DC accuracy is of importance.

The LMP7731 has a high gain bandwidth of 22 MHz. This wide bandwidth enables use of the amplifier at higher gain settings while retaining usable bandwidth for the application. This is particularly beneficial when system designers need to use sensors with very limited output voltage range as it allows larger gains in one stage which in turn increases the signal to noise ratio.

The LMP7731 has proprietary input bias cancellation circuitry on the input stages. This allows the LMP7731 to have only about 1.5 nA bias current with a bipolar input stage. This low input bias current, paired with the inherent lower input voltage noise of bipolar input stages makes the LMP7731 an excellent choice for precision applications. The combination of low input bias current, and low input voltage noise enables the user to achieve unprecedented accuracy and higher signal integrity.

Texas Instruments is heavily committed to precision amplifiers and the market segment they serve. Technical support and extensive characterization data are available for sensitive applications or applications with a constrained error budget.

The LMP7731 is offered in the space saving 5-Pin SOT-23 and 8-Pin SOIC packages. These small packages are ideal solutions for area constrained PC boards and portable electronics.

#### INPUT BIAS CURRENT CANCELLATION

The LMP7731 has proprietary input bias current cancellation circuitry on their input stages.

The LMP7731 has rail-to-rail input. This is achieved by having two input stages in parallel. Figure 44 shows only one of the input stages as the circuitry is symmetrical for both stages.

Figure 44 shows that as the common mode voltage gets closer to one of the extreme ends, current  $I_1$  significantly increases. This increased current shows as an increase in voltage drop across resistor  $R_1$  equal to  $I_1*R_1$  on  $IN^+$  of the amplifier. This voltage contributes to the offset voltage of the amplifier. When common mode voltage is in the mid-range, the transistors are operating in the linear region and  $I_1$  is significantly small. The voltage drop due to  $I_1$  across  $R_1$  can be ignored as it is orders of magnitude smaller than the amplifier's input offset voltage.

As the common mode voltage gets closer to one of the rails, the offset voltage generated due to I<sub>1</sub> increases and becomes comparable to the amplifiers offset voltage.

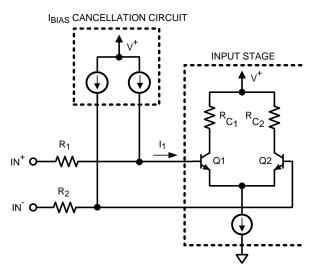


Figure 44. Input Bias Current Cancellation

Product Folder Links: LMP7731

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### INPUT VOLTAGE NOISE MEASUREMENT

The LMP7731 has very low input voltage noise. The peak-to-peak input voltage noise of the LMP7731 can be measured using the test circuit shown in Figure 45

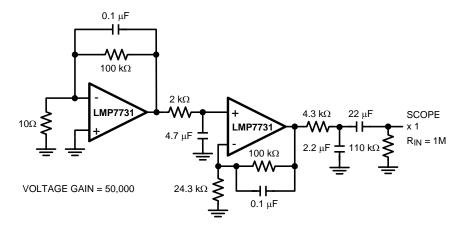


Figure 45. 0.1 Hz to 10 Hz Noise Test Circuit

The frequency response of this noise test circuit at the 0.1 Hz corner is defined by only one zero. The test time for the 0.1 Hz to 10 Hz noise measurement using this configuration should not exceed 10 seconds, as this time limit acts as an additional zero to reduce or eliminate the noise contributions of noise from frequencies below 0.1 Hz.

Figure 46 shows typical peak-to-peak noise for the LMP7731 measured with the circuit in Figure 45 for the LMP7731.

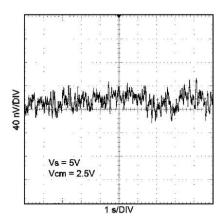


Figure 46. 0.1 Hz to 10 Hz Input Voltage Noise

Measuring the very low peak-to-peak noise performance of the LMP7731, requires special testing attention. In order to achieve accurate results, the device should be warmed up for at least five minutes. This is so that the input offset voltage of the op amp settles to a value. During this warm up period, the offset can typically change by a few  $\mu V$  because the chip temperature increases by about 30°C. If the 10 seconds of the measurement is selected to include this warm up time, some of this temperature change might show up as the measured noise. Figure 47 shows the start-up drift of five typical LMP7731 units.



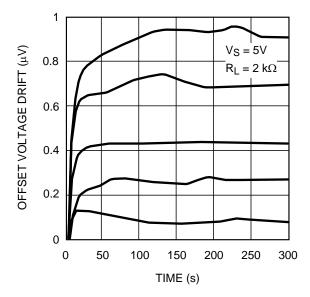


Figure 47. Start-Up Input Offset Voltage Drift

During the peak-to-peak noise measurement, the LMP7731 must be shielded. This prevents offset variations due to airflow. Offset can vary by a few nV due to this airflow and that can invalidate measurements of input voltage noise with a magnitude which is in the same range. For similar reasons, sudden motions must also be restricted in the vicinity of the test area. The feed-through which results from this motion could increase the observed noise value which in turn would invalidate the measurement.

#### **DIODES BETWEEN THE INPUTS**

The LMP7731 has a set of anti-parallel diodes between the input pins as shown in Figure 48. These diodes are present to protect the input stage of the amplifier. At the same time, they limit the amount of differential input voltage that is allowed on the input pins. A differential signal larger than the voltage needed to turn on the diodes might cause damage to the diodes. The differential voltage between the input pins should be limited to ±3 diode drops or the input current needs to be limited to ±20 mA.

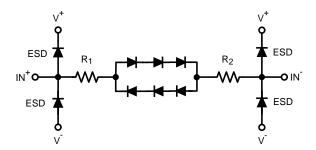


Figure 48. Anti-Parallel Diodes between Inputs

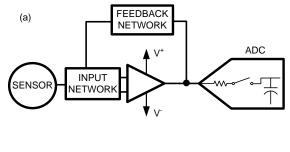
### **DRIVING AN ADC**

Analog to Digital Converters, ADCs, usually have a sampling capacitor on their input. When the ADC's input is directly connected to the output of the amplifier a charging current flows from the amplifier to the ADC. This charging current causes a momentary glitch that can take some time to settle. There are different ways to minimize this effect. One way is to slow down the sampling rate. This method gives the amplifier sufficient time to stabilize its output. Another way to minimize the glitch caused by the switch capacitor is to have an external capacitor connected to the input of the ADC. This capacitor is chosen so that its value is much larger than the internal switching capacitor and it will hence provide the voltage needed to quickly and smoothly charge the



ADC's sampling capacitor. Since this large capacitor will be loading the output of the amplifier as well, an isolation resistor is needed between the output of the amplifier and this capacitor. The isolation resistor,  $R_{ISO}$ , separates the additional load capacitance from the output of the amplifier and will also form a low-pass filter and can be designed to provide noise reduction as well as anti-aliasing. The drawback to having  $R_{ISO}$  is that it reduces signal swing since there is some voltage drop across it.

Figure 49 (a) shows the ADC directly connected to the amplifier. To minimize the glitch in this setting, a slower sample rate needs to be used. Figure 49 (b) shows R<sub>ISO</sub> and an external capacitor used to minimize the glitch.



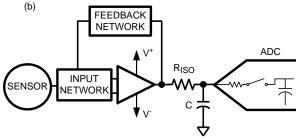


Figure 49. Driving an ADC



## **REVISION HISTORY**

Cł	nanges from Revision D (March 2013) to Revision E	Paç	ge
•	Changed layout of National Data Sheet to TI format		17





11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
LMP7731MA/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		LMP77 31MA	Samples
LMP7731MAX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		LMP77 31MA	Samples
LMP7731MF/NOPB	ACTIVE	SOT-23	DBV	5	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	АҮЗА	Samples
LMP7731MFE/NOPB	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	АҮЗА	Samples
LMP7731MFX/NOPB	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	АҮЗА	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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<sup>(3)</sup> MSL. Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



# **PACKAGE OPTION ADDENDUM**

11-Apr-2013

In no event shall TI's liability	arisino	out of such information	n exceed the total pu	urchase price o	of the TI part(s	at issue in this	document sold by	TI to Customer on an annual basis.

# PACKAGE MATERIALS INFORMATION

www.ti.com 20-Dec-2016

## TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difficults are florifinal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMP7731MAX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMP7731MF/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7731MFE/NOPB	SOT-23	DBV	5	250	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMP7731MFX/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

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\*All dimensions are nominal

7 III GITTIOTIOTOTIO GITO TTOTTIITIGI							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMP7731MAX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LMP7731MF/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LMP7731MFE/NOPB	SOT-23	DBV	5	250	210.0	185.0	35.0
LMP7731MFX/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4073253/P





SMALL OUTLINE TRANSISTOR



### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. Reference JEDEC MO-178.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 7. Board assembly site may have different recommendations for stencil design.



# D (R-PDSO-G8)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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